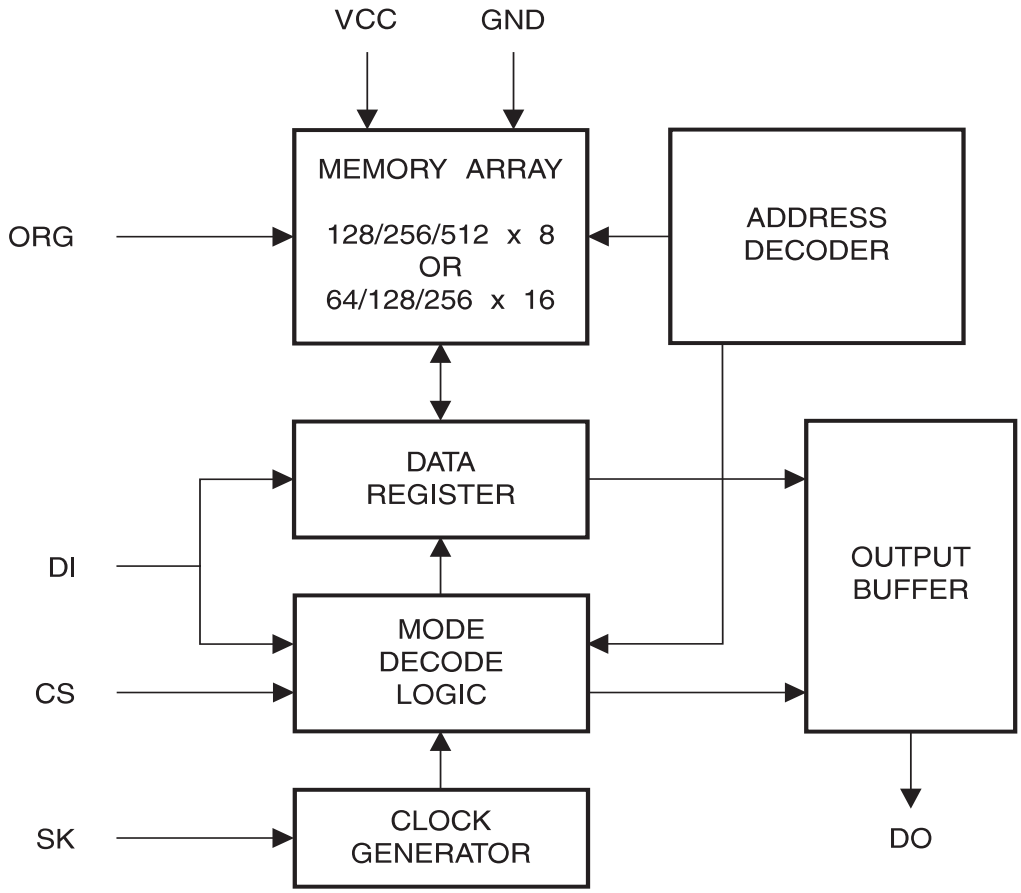
3. Absolute Maximum Ratings*

Operating Temperature	–55°C to +125°C
Storage Temperature	–65°C to +150°C
Voltage on Any Pin with Respect to Ground	–1.0V to +7.0V
Maximum Operating Voltage	6.25V
DC Output Current	5.0 mA

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

Figure 3-1. Block Diagram



Note: When the ORG pin is connected to VCC, the “x 16” organization is selected. When it is connected to ground, the “x 8” organization is selected. If the ORG pin is left unconnected and the application does not load the input beyond the capability of the internal 1 Meg ohm pullup, then the “x 16” organization is selected.

For the AT93C46, if “x 16” organization is the mode of choice and Pin 6 (ORG) is left unconnected, Atmel recommends using the AT93C46A device. For more details, see the AT93C46A datasheet.

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Table 3-1. Pin Capacitance[1]

Applicable over recommended operating range from T_A = 25°C, f = 1.0 MHz, V_{CC} = +5.0V (unless otherwise noted)

Symbol	Test Conditions	Max	Units	Conditions
C_{OUT}	Output Capacitance (DO)	5	pF	V_{OUT} = 0V
C_{IN}	Input Capacitance (CS, SK, DI)	5	pF	V_{IN} = 0V

Note: 1. This parameter is characterized and is not 100% tested.

Table 3-2. DC Characteristics

Applicable over recommended operating range from: T_A = –40°C to +125°C, V_{CC} = +2.7V to +5.5V (unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Typ	Max	Unit
V_{CC1}	Supply Voltage			2.7		5.5	V
V_{CC2}	Supply Voltage			4.5		5.5	V
I_{CC}	Supply Current	V_{CC} = 5.0V	READ at 1.0 MHz		0.5	2.0	mA
			WRITE at 1.0 MHz		0.5	2.0	mA
I_{SB1}	Standby Current	V_{CC} = 2.7V	CS = 0V		6.0	10.0	µA
I_{SB2}	Standby Current	V_{CC} = 5.0V	CS = 0V		10.0	15.0	µA
I_{IL}	Input Leakage	V_{IN} = 0V to V_{CC}			0.1	1.0	µA
I_{OL}	Output Leakage	V_{IN} = 0V to V_{CC}			0.1	1.0	µA
V_{IL1}[1]	Input Low Voltage	2.7V ≤ V_{CC} ≤ 5.5V		–0.6		0.8	
V_{IH1}[1]	Input High Voltage			2.0		V_{CC} + 1	V
V_{OL1}	Output Low Voltage	2.7V ≤ V_{CC} ≤ 5.5V	I_{OL} = 2.1 mA			0.4	V
V_{OH1}	Output High Voltage		I_{OH} = –0.4 mA	2.4			V

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested.

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Table 3-3. AC Characteristics

Applicable over recommended operating range from T_A = –40°C to + 125°C, V_{CC} = As Specified, CL = 1 TTL Gate and 100 pF (unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Typ	Max	Units
f_{SK}	SK Clock Frequency	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		0 0		2 1	MHz
t_{SKH}	SK High Time	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		250 250			ns
t_{SKL}	SK Low Time	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		250 250			ns
t_{CS}	Minimum CS Low Time	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$		250 250			ns
t_{CSS}	CS Setup Time	Relative to SK	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$	50 50			ns
t_{DIS}	DI Setup Time	Relative to SK	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$	100 100			ns
t_{CSH}	CS Hold Time	Relative to SK		0			ns
t_{DIH}	DI Hold Time	Relative to SK	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$	100 100			ns
t_{PD1}	Output Delay to ‘1’	AC Test	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			250 500	ns
t_{PD0}	Output Delay to ‘0’	AC Test	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			250 500	ns
t_{SV}	CS to Status Valid	AC Test	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			250 250	ns
t_{DF}	CS to DO in High Impedance	AC Test CS = V_{IL}	$4.5V \le V_{CC} \le 5.5V$ $2.7V \le V_{CC} \le 5.5V$			100 150	ns
t_{WP}	Write Cycle Time		$2.7V \le V_{CC} \le 5.5V$		3	10	ms
Endurance(1)	5.0V, 25°C			1M			Write Cycles

Note: 1. This parameter is ensured by characterization only.

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Table 3-4. Instruction Set for the AT93C46

Instruction	SB	Op Code	Address		Data		Comments
			x 8	x 16	x 8	x 16	
READ	1	10	A_6 - A_0	A_5 - A_0			Reads data stored in memory, at specified address
EWEN	1	00	11XXXXX	11XXXX			Write enable must precede all programming modes
ERASE	1	11	A_6 - A_0	A_5 - A_0			Erase memory location A_n - A_0
WRITE	1	01	A_6 - A_0	A_5 - A_0	D_7 - D_0	D_{15} - D_0	Writes memory location A_n - A_0
ERAL	1	00	10XXXXX	10XXXX			Erases all memory locations. Valid only at V_{CC} = 4.5V to 5.5V
WRAL	1	00	01XXXXX	01XXXX	D_7 - D_0	D_{15} - D_0	Writes all memory locations. Valid only at V_{CC} = 4.5V to 5.5V
EWDS	1	00	00XXXXX	00XXXX			Disables all programming instructions

Note: The Xs in the address field represent don't care values and must be clocked.

Table 3-5. Instruction Set for the AT93C56[1] and AT93C66[2]

Instruction	SB	Op Code	Address		Data		Comments
			x 8	x 16	x 8	x 16	
READ	1	10	A_8 - A_0	A_7 - A_0			Reads data stored in memory, at specified address
EWEN	1	00	11XXXXXXX	11XXXXXX			Write enable must precede all programming modes
ERASE	1	11	A_8 - A_0	A_7 - A_0			Erase memory location A_n - A_0
WRITE	1	01	A_8 - A_0	A_7 - A_0	D_7 - D_0	D_{15} - D_0	Writes memory location A_n - A_0
ERAL	1	00	10XXXXXXX	10XXXXXX			Erases all memory locations. Valid only at V_{CC} = 4.5V to 5.5V
WRAL	1	00	01XXXXXXX	01XXXXXX	D_7 - D_0	D_{15} - D_0	Writes all memory locations. Valid only at V_{CC} = 5.0V ±10% and Disable Register cleared
EWDS	1	00	00XXXXXXX	00XXXXXX			Disables all programming instructions

Note: 1. This device is not recommended for new designs. Please refer to AT93C56A.
2. This device is not recommended for new designs. Please refer to AT93C66A.
3. The Xs in the address field represent *don't care* values and must be clocked.

4. Functional Description

The AT93C46/56/66 is accessed via a simple and versatile 3-wire serial communication interface. Device operation is controlled by seven instructions issued by the host processor. *A valid instruction starts with a rising edge of CS* and consists of a Start Bit (logic "1") followed by the appropriate Op Code and the desired memory Address location.

READ (READ): The Read (READ) instruction contains the address code for the memory location to be read. After the instruction and address are decoded, data from the selected memory

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location is available at the serial output pin DO. Output data changes are synchronized with the rising edges of serial clock SK. It should be noted that a dummy bit (logic “0”) precedes the 8- or 16-bit data output string.

ERASE/WRITE (EWEN): To assure data integrity, the part automatically goes into the Erase/Write Disable (EWDS) state when power is first applied. An Erase/Write Enable (EWEN) instruction must be executed first before any programming instructions can be carried out. Please note that once in the EWEN state, programming remains enabled until an EWDS instruction is executed or V_{CC} power is removed from the part.

ERASE (ERASE): The Erase (ERASE) instruction programs all bits in the specified memory location to the logical “1” state. The self-timed erase cycle starts once the ERASE instruction and address are decoded. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). A logic “1” at pin DO indicates that the selected memory location has been erased, and the part is ready for another instruction.

WRITE (WRITE): The Write (WRITE) instruction contains the 8 or 16 bits of data to be written into the specified memory location. The self-timed programming cycle, t_{WP}, starts after the last bit of data is received at serial data input pin DI. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). A logic “0” at DO indicates that programming is still in progress. A logic “1” indicates that the memory location at the specified address has been written with the data pattern contained in the instruction and the part is ready for further instructions. *A Ready/Busy status cannot be obtained if the CS is brought high after the end of the self-timed programming cycle, t_{WP}.*

ERASE ALL (ERAL): The Erase All (ERAL) instruction programs every bit in the memory array to the logic “1” state and is primarily used for testing purposes. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). The ERAL instruction is valid only at V_{CC} = 5.0V ± 10%.

WRITE ALL (WRAL): The Write All (WRAL) instruction programs all memory locations with the data patterns specified in the instruction. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (t_{CS}). The WRAL instruction is valid only at V_{CC} = 5.0V ± 10%.

ERASE/WRITE DISABLE (EWDS): To protect against accidental data disturb, the Erase/Write Disable (EWDS) instruction disables all programming modes and should be executed after all programming operations. The operation of the Read instruction is independent of both the EWEN and EWDS instructions and can be executed at any time.

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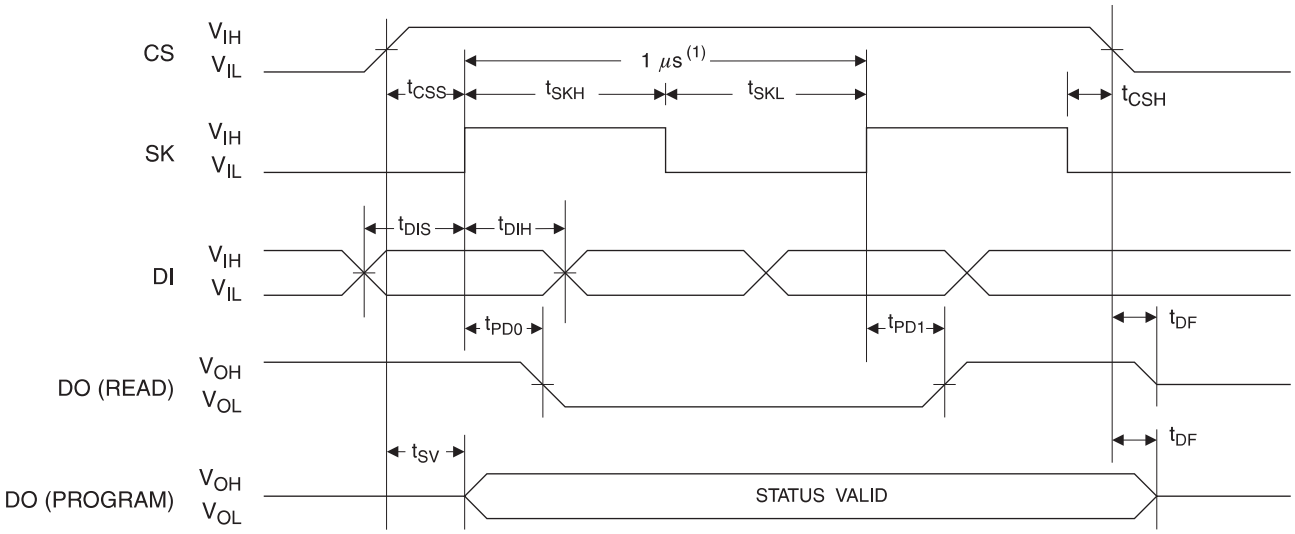
5. Timing Diagrams

Figure 5-1. Synchronous Data Timing



Note: 1. This is the minimum SK period.

Table 5-1. Organization Key for Timing Diagrams

	AT93C46 (1K)		AT93C56 (2K)[1]		AT93C66 (4K)[2]	
I/O	**x 8**	**x 16**	**x 8**	**x 16**	**x 8**	**x 16**
A_N	A_6	A_5	A_8[3]	A_7[4]	A_8	A_7
D_N	D_7	D_{15}	D_7	D_{15}	D_7	D_{15}

Notes:
1. This device is not recommended for new designs. Please refer to AT93C56A.
2. This device is not recommended for new designs. Please refer to AT93C66A.
3. A_8 is a *don't care* value, but the extra clock is required.
4. A_7 is a *don't care* value, but the extra clock is required.

Figure 5-2. READ Timing

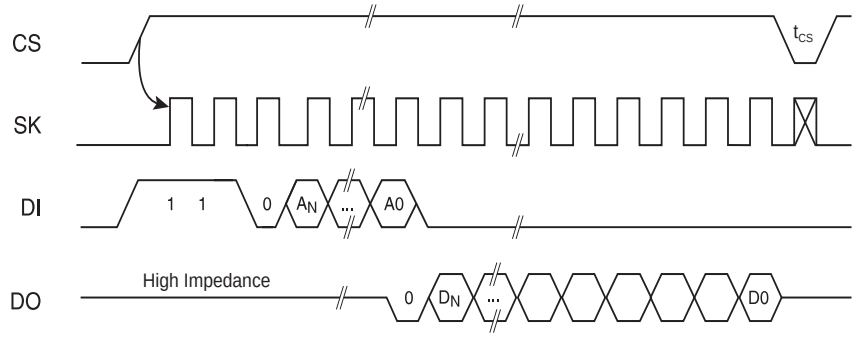


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Figure 5-3. EWEN Timing

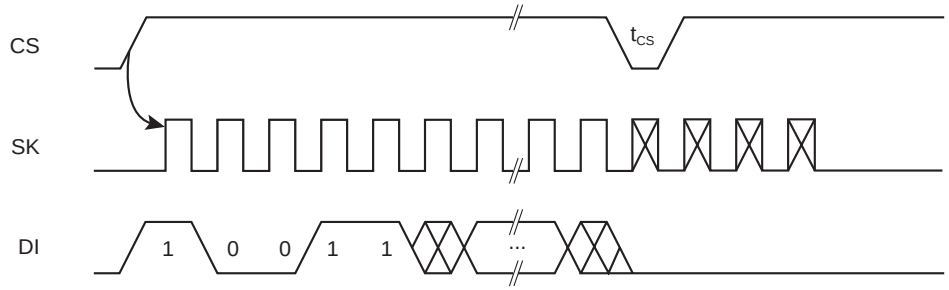


Figure 5-4. EWDS Timing

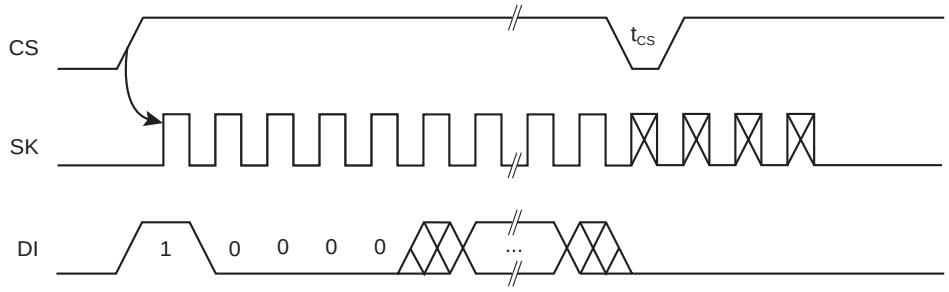


Figure 5-5. WRITE Timing

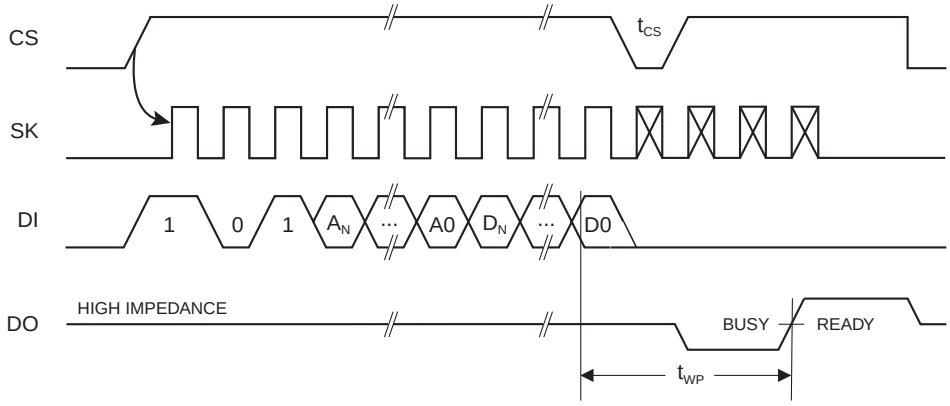
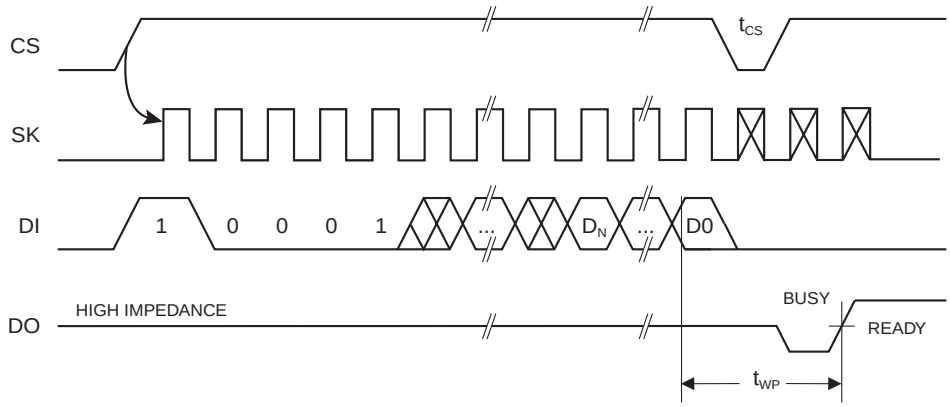


Figure 5-6. WRAL Timing[(1)]



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Note: 1. Valid only at V_{CC} = 4.5V to 5.5V.

Figure 5-7. ERASE Timing

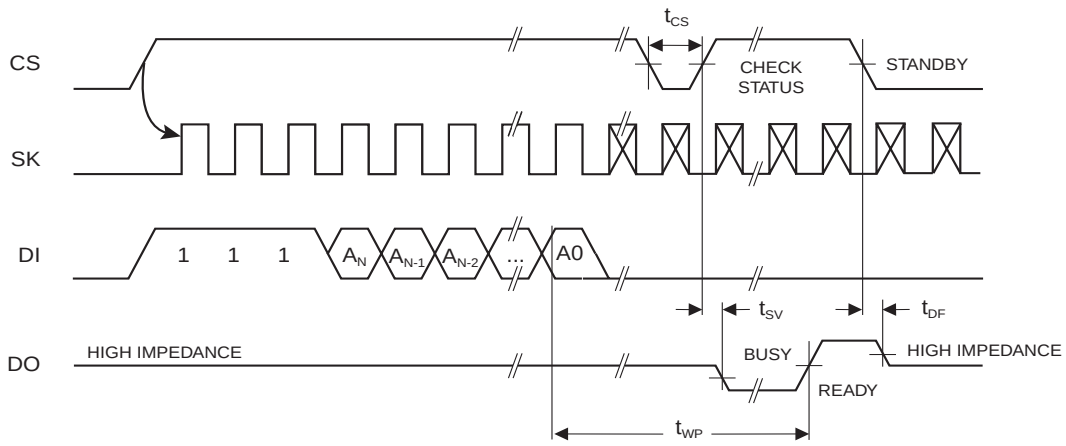
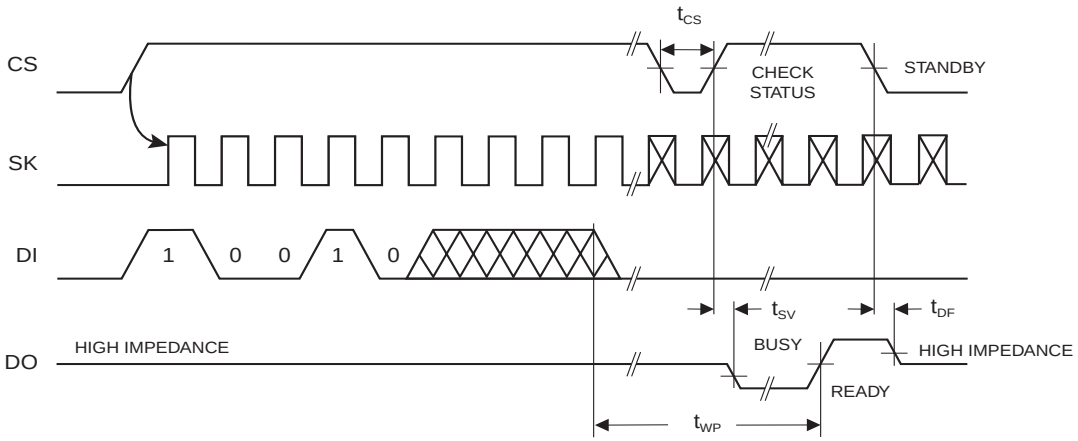


Figure 5-8. ERAL Timing[1]



Note: 1. Valid only at V_{CC} = 4.5V to 5.5V.

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6. AT93C46 Ordering Information

Ordering Code	Package	Operation Range
AT93C46-10SQ-2.7 AT93C46-10TQ-2.7	8S1 8A2	Lead-Free/Halogen Free Automotive Temperature (–40°C to 125°C)

Package Type	
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
8A2	8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)
Options	
–2.7	Low Voltage (2.7V to 5.5V)

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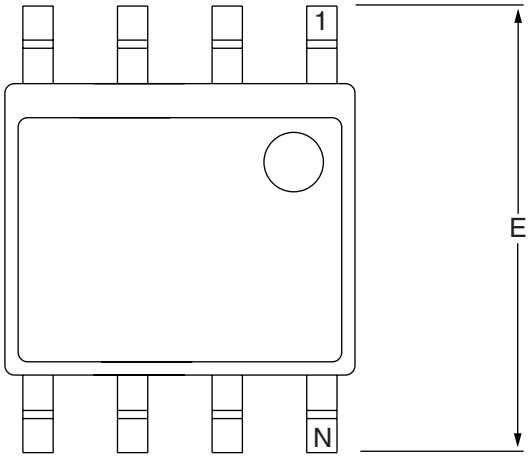
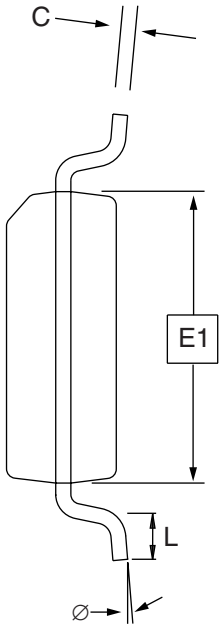
Packaging Information

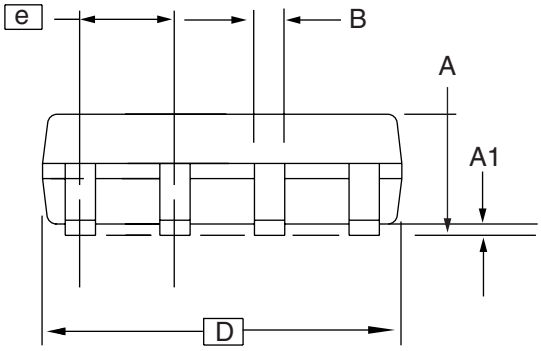
8S1 – JEDEC SOIC



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	1.35	–	1.75	
A1	0.10	–	0.25	
b	0.31	–	0.51	
C	0.17	–	0.25	
D	4.80	–	5.00	
E1	3.81	–	3.99	
E	5.79	–	6.20	
e	1.27 BSC			
L	0.40	–	1.27	
∅	0°	–	8°	

Note: These drawings are for general information only. Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.

10/7/03

	TITLE	DRAWING NO.	REV.
1150 E. Cheyenne Mtn. Blvd. Colorado Springs, CO 80906	**8S1**, 8-lead (0.150" Wide Body), Plastic Gull Wing Small Outline (JEDEC SOIC)	8S1	B

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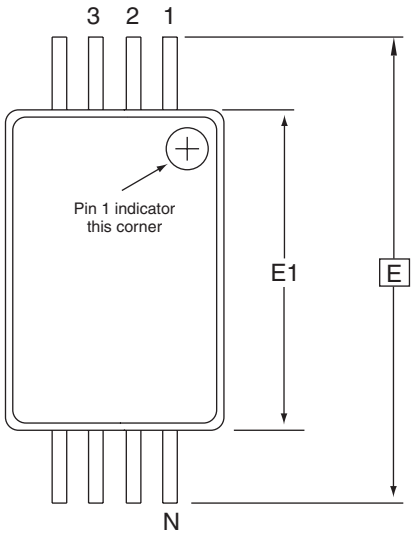
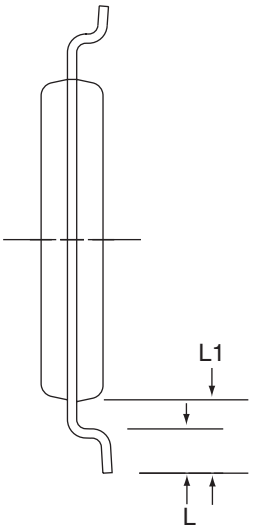
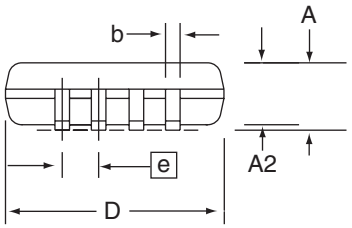
8A2 - TSSOP



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
D	2.90	3.00	3.10	2, 5
E		6.40 BSC		
E1	4.30	4.40	4.50	3, 5
A	–	–	1.20	
A2	0.80	1.00	1.05	
b	0.19	–	0.30	4
e		0.65 BSC		
L	0.45	0.60	0.75	
L1		1.00 REF		

Notes:
1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15 mm (0.006 in) per side.
3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25 mm (0.010 in) per side.
4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07 mm.
5. Dimension D and E1 to be determined at Datum Plane H.

5/30/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**8A2**, 8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)	8A2	B

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Revision History

Doc. Rev.	Date	Comments
5125C	11/2007	Updated to new template Changed max value of V_{il1}, V_{ih1}, and t_{DF}
5125B	1/2007	Implemented revision history Removed PDIP package offering Removed Pb'd parts

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